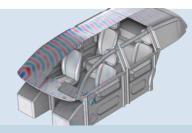
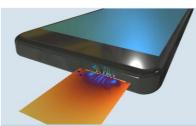
Acoustics Module

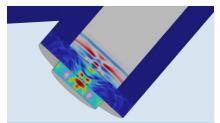
The Acoustics Module



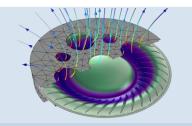
Pressure Acoustics Classical acoustics, attenuation, porous media models, with a variety of modeling formulations



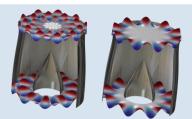
Thermoviscous Acoustics Microacoustics, microtransducers, MEMS, thermal and viscous boundary layer losses, etc.



Elastic Waves Elastic waves in solids; mixed pressure and elastic waves in porous materials

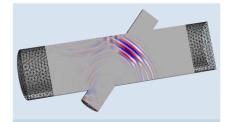


Acoustic-Structure Interaction Full vibroacoustics analysis with easy and intuitive built-in multiphysics couplings

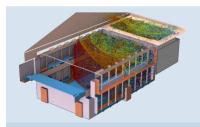


Aeroacoustics

Convected acoustics, Linearized Navier-Stokes and Linearized Euler formulations, convected wave equation, flow-induced noise, and mode extraction

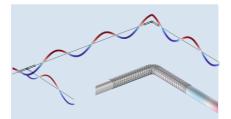


Ultrasound Ultrasound propagation, piezoelectric transducers, linear and nonlinear



Geometrical Acoustics

High-frequency methods using ray tracing for room acoustics and more; full wave to ray couplings



Pipe Acoustics

Wave propagation in 1D pipe structures with background flow effects; 1D to 3D coupling for system simulation



COMSOL Multiphysics[®] Version 6.0

A new paradigm in multiphysics modeling

- To provide an all-encompassing workspace or modeling environment of the product design workflow
- Equation-based modeling

Model Builder

Supports all facets of the modeling process

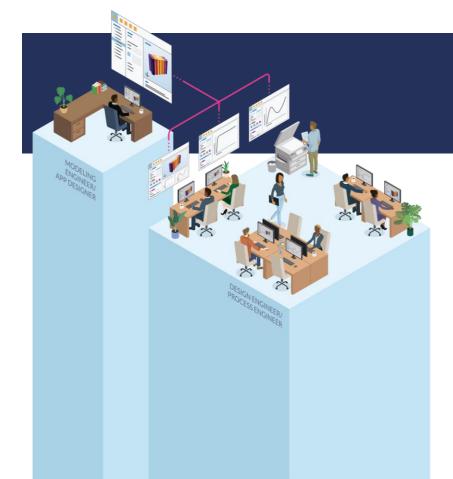
- Platform feature utilizing physics interfaces
 - Creates a framework for extendable modeling – multiphysics
 - Add-on modules

Model

Builder

Graphics

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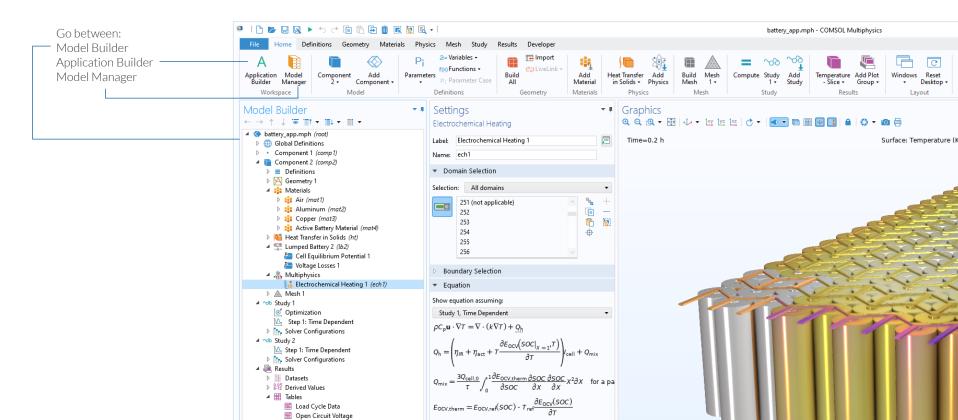


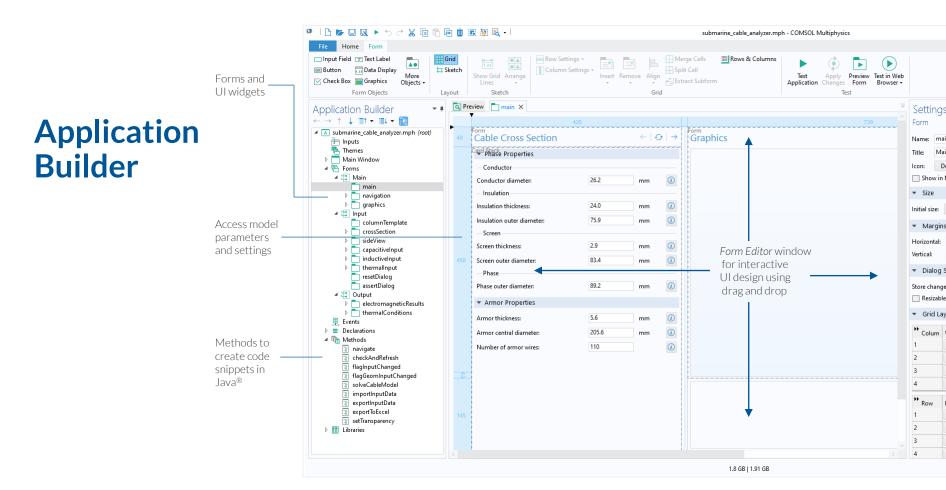
Application Builder

Supports extending modeling to specific engineering and technical applications

- Intuitive and flexible app development environment
- Collaborative, enhanced by the Model Manager

Application Builder







Simulation Apps

Provide data, such as designs, material data, and instructions

- Wide deployment options allowing broad usage by design engineers, operators, and technicians
- App results data informs manufacturing parameters

Simulation Applications

			Graph	ics		
	11	Untitled.mph - Li Battery Pack Designer				
	Battery Battery Compute	Open Circuit Voltage ① Cell Voltage Experimental Data ① Voltage Losse Cell State-of-Charge Battery Cell	es Update Mesh Co	■ □	Air Doct	
	Battery Pack		Graphics			
Design —	🔻 Design		@. @. ⊕. ₹ ₫	🗸 🗸 🖾 kā kara kara kara kara kara kara kara k	💌 🕶 💌 🔲 🚺 🔇	
	Packing type:	Offset 🔻	Time=0.2 h		Surface: Temperature (K	
	Number of batteries in series:	20 🔹				
	Number of batteries in parallel:	10 🔻			_	
Operating conditions	Battery diameter:	21 mm		Numerical Results		
	Battery height:	70 mm				
	Terminal diameter:	6 mm		Export to Text Export to Excel	Clear Table	
		-		₩ Variable name	Solution 1	
	Terminal thickness:	1 mm		Maximum battery temperature [degC]	44.7612	
	Bus bar thickness:	1 mm		Average battery temperature [degC] Battery pack volume [m^3]	30.6030	
	Serial connector width:	3 mm		Battery capacity [A*h]	4	
		-		Optimality tolerance	0.01	
	Parallel connector width:	1 mm		Ohmic overpotential at 1C [V] Diffusion time constant [s]	0.0045162	
	 Conditions 			Dimensionless charge exchange current	0.86471	
				Packing type	Offset	
	C rate:	4		Batteries in series Batteries in parallel	20	
		1		Battery diameter [mm]	21	
	Initial state-of-charge:	1		Battery height [mm] Terminal diameter [mm]	70	
	Final state-of-charge:	0.2		Bus bar thickness [mm]	1	
		20 °C		Serial connector width [mm]	3	
	Initial/external temperature:	20 C		Parallel connector width [mm]	2000	
	Heat transfer coefficient, sides:	30 W/(m ² ·K)		Battery density [kg/m^3] Battery heat capacity [J/(kg*K)]	1400	
	Heat transfer coefficient, top:	30 W/(m ² ·K)		Thermal conductivity, in plane [W/(m*K)]	30	
			_	Thermal conductivity, cross plane [W/(m*K)] C rate	4	
	Heat transfer coefficient, bottom:	5 W/(m ² ·K)	Z	Initial state of charge		
Results				Final state-of-charge	0.2	
RESUILS			х у	Initial/external temperature [degC]	20	
			0	Heat transfer coefficient, sides [W/(m^2*K)] Heat transfer coefficient, top [W/(m^2*K)]	30	
				Heat transfer coefficient, bottom [W/(m^2*K)]	30	
				Mesh size	Normal	



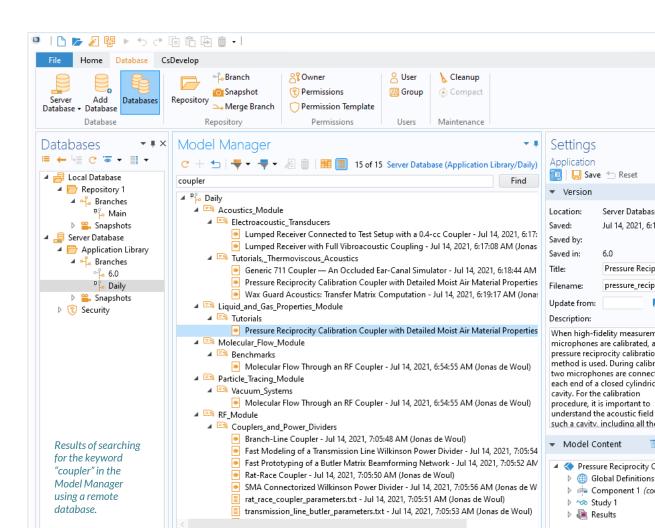
Model Manager

Democratization of simulation

- Collaborative and data-informed modeling process
- Resulting simulations accessible to all levels, at any stage of the product design life cycle

Model Manager

- Included in COMSOL Multiphysics
- Simulation data management
- Version control
- Efficient storage
- Searching model contents
- Access control
- Local or remote database

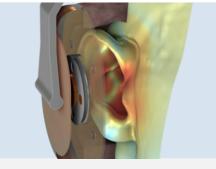


The Acoustics Module - Is It Really "Multi"?

 $\nabla \cdot \left(-\frac{1}{\rho_{c}} (\nabla \rho_{t} \cdot \mathbf{q}_{d}) \right) \cdot \frac{k_{eq}^{2} \rho_{t}}{\rho_{c}} = Q_{m}$ $\frac{1}{\rho c^{2} \partial t} + \nabla \cdot \left[\left(1 + \frac{\beta \rho_{t}}{\rho c^{2}} \right) \mathbf{u}_{t} \right] = Q_{m}$ $\rho \frac{\partial \mathbf{u}_{t}}{\partial t} + \nabla \cdot (\rho_{t} \mathbf{l}) = \mathbf{q}_{d}$ $\beta \frac{\partial \mathbf{u}_{t}}{\partial t} + \nabla \cdot (\rho_{t} \mathbf{l}) = \mathbf{q}_{d}$ $\beta = 1 + \frac{B}{2A}$ $\rho_{0} C_{p} (i\omega T_{t} + \mathbf{u}_{t} \cdot \nabla T_{0}) - \alpha_{p} T_{0} (i\omega \rho_{t} + \mathbf{u}_{t} \cdot \nabla \rho_{0}^{2}) = \nabla \cdot (k \nabla T_{t}) + Q$

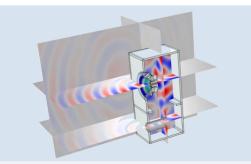
Multiformulation

- Helmholtz and wave equations
- Thermoviscous acoustics
- Linearized Navier-Stokes formulation
- Linearized Euler formulation
- Optimization
- Moving mesh and frames



Multiphysics

- Vibroacoustics (acoustic-structure)
- Piezoelectric materials
- Porous materials (Biot's equations)
- Aeroacoustics (convected acoustics)
- Electroacoustics (fully coupled or lumped)



Multimethod

- Finite element method (FEM)
- Boundary element method (BEM)
- High-frequency BEM (HFBEM)
- Hybrid FEM-BEM modeling
- Ray tracing
- Discontinuous Galerkin (dG-FEM), time explicit

Ultrasonic Car Parking Sensor

Multiphysics

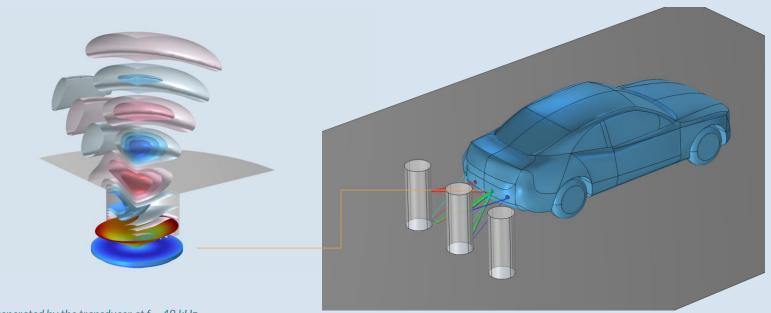
- Piezoelectricity
- Acoustic-structure interaction

Multimethod

- Finite elements
- Ray tracing



Ultrasonic Car Parking Sensor



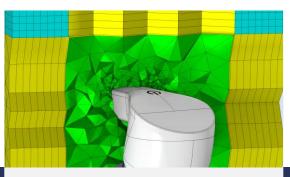
Acoustic pressure generated by the transducer at f = 48 kHz.

The Latest News (COMSOL Multiphysics[®] Version 6.0)



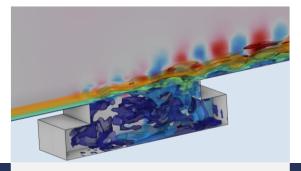
 \wedge

- Ultrasonic piezo transducers
- Multiphysics
- Time explicit higher-order formulation
- Hybrid FEM-dG method



Physics-Controlled Mesh

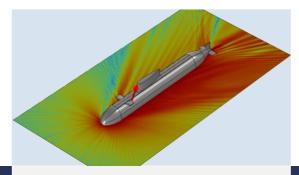
- Automated best-practices-based meshing
- Physics and material parameters analyzed



Introducing Flow-Induced Noise

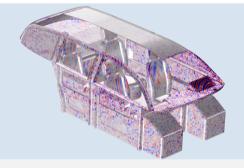
- Lighthill's acoustic analogy
- Acoustic wave equation (AWE)
- Multiphysics coupling and transient mapping

The Latest News (COMSOL Multiphysics[®] Version 6.0)



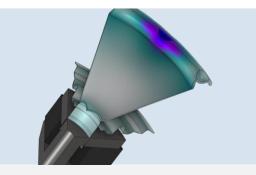
High-Frequency BEM

- Solve scattering and radiation problems efficiently
- Acoustically large problems



Performance

- Improved performance for solving large problems
- Improved automatic iterative solver suggestions

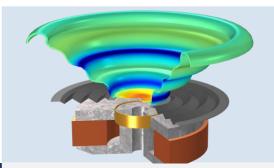


Optimization

- Dedicated functionality for acoustic optimization
- Improved handling for fixed driver mounts (rotation, scaling, and translation)

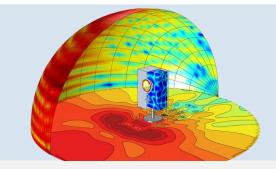
Loudspeakers

Analyses for Different Stages of the Development Cycle



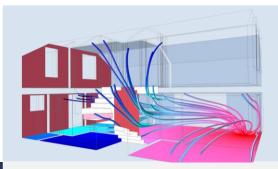
Speaker Driver Design

- Vibroelectroacoustic analysis: Magnetic Fields; Pressure Acoustics, Frequency Domain; and Solid Mechanics in the frequency domain, all fully coupled
- Nonlinear distortion: full transient study with moving mesh



Waveguide and Cabinet Design

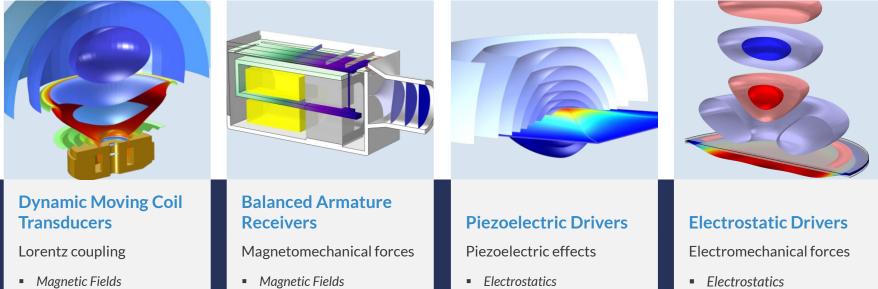
- Vibroacoustic analysis: Pressure Acoustics, Frequency Domain for the cabinet; Pressure Acoustics, Boundary Elements for the surrounding space; Solid Mechanics and Shell for the speaker components
- Frequency domain and eigenfrequency studies



Room Acoustics

- Pressure Acoustics, Frequency Domain for lower frequencies
- Two Geometrical Acoustics interfaces:
 - Ray Acoustics interface with a ray tracing study
 - Acoustic Diffusion Equation interface with an eigenvalue, stationary, or timedependent study

Multiphysics Couplings for Different Types of Speaker Drivers



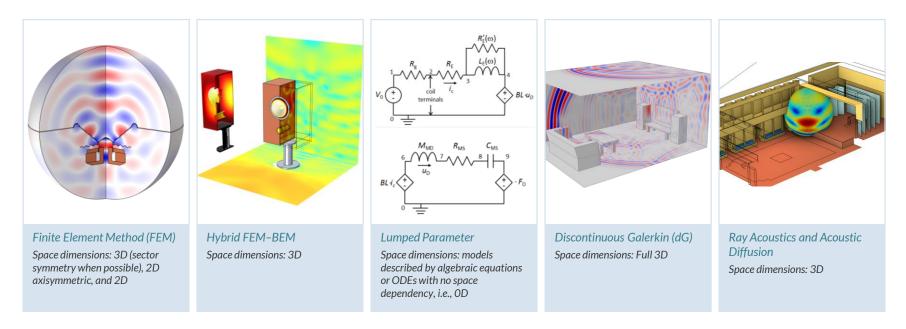
Solid Mechanics

Solid Mechanics

- Solid Mechanics

- Solid Mechanics Ξ.

Numerical Methods and Space Dimensions



Speaker driver design

Room acoustics

EXAMPLES Full Vibroelectroacoustic Analysis

A full vibroelectroacoustic simulation of a balanced armature transducer — a high-performance miniature loudspeaker — uses the built-in *Magnetomechanical Forces* multiphysics coupling.

ApplicationModel SolidComponent Component ModelParameterCost ParameterBuild Add AllSolid Material Build Add AllSolid Material Build Material GeometryBuild Material Build Material GeometryBuild Material Build Material GeometryBuild Material Build Material GeometryBuild Material Build Material GeometryBuild Material GeometryBuild Material GeometryBuild Material GeometryBuild Material GeometryCompute Study 3- Mee Complet Study 3- Mee Compute Study 3- Mee Comple Study 3- Mee Compute Study 3- Mee Comple Study 3- Mee Component 1 Component 1 (com 1) Component 1 (com 1) Component 1 Component	🔍 🗅 🃂 🗔 🔍 🕨 🕤 🤭 🛅 🛱 🗰 🗮 🕷 🔍 -			balanced_armature_transducer_60.mph - COM
A gplication Builder Manager Builder Manager WorkspaceComponent Add 1 · Component - ModelParameters P parameter Case P parameter CaseBuild Build Compute Study Build Compute Study GeometrySolid - Add Methins PhysicsBuild Methins MethinsSolid - Add MethinsBuild Add MethinsSolid - Add MethinsBuild Methins StudyCompute Study 3- Met Compute Study MethinsModelWorkspaceModelDefinitionsCompute Study DefinitionsStudyMethins StudyStudyMethins StudyMethinsStudyModelT = T + T + T + T + T + T + T + T + T +	File Home Definitions Geometry Materials Physics	Mesh Study Results Developer		
$ \begin{array}{c} & & & & & & & & & & & & & & & & & & &$	A E Component Add Parameters	≫Functions - P₁ Parameter Case Build All C⊅ LiveLink - Build	Add Material	Solid Add Build Mesh: Compute Study 3 - Mecha ial Mechanics + Physics Mesh Solid + Compliance
Implete Staw Armature Amplete's Law Armature Gauge Fixing for A-Field 1 Image: Staw Armature Gauge Fixing for A-Field 1 Image: Staw Armature Image: Armature Boundary 1 (asb 1) Image: Staw Armature Image: Staw Armature Image: Armature Boundary 1 (asb 1) Image: Staw Armature	 balanced_armature_transducer_60.mph (root) billoab Definitions Component 1 (comp 1) Component 1 (comp 1) Component 1 (comp 1) Component 1 (comp 1) Second Hard Boundary (Wall) Pressure Acoustics 1 Sound Hard Boundary (Wall) 1 Initial Values 1 Soymetry 1 Narrow Region Acoustics 3 Impedance 1 - Vent Lumped Port 1 - Tube and Coupler Maperies Law: Pole Piece Ampier's Law: Pole Piece Sumper's Law: Pole Piece Sumptier's Law: Pole Piece Super's Law: Commont Magnet Ampier's Law: Pole Piece Support Step 1: Coli Geometry Analysis Step 2: Stationary Step 2: Stationary Step 3: Frequency Response Step 3: Frequency Comain Perturbation Subdy 3 - Mechanical Modes Stydy 3 - Mechanical Modes 	Magnetomechanical Forces Label: Magnetomechanical Forces 1 Name: immf1 Domain Selection • Equation Show equation assuming: Study 1 - Frequency Response, Coil Geometry Analysis $W_{EM} = W_s(C) + \frac{1}{2} (\mu_0 \mu_r J)^{-1}C: (B \otimes B)$ $C = F^T F, J = det(F)$ $S = 2 \frac{\partial W_{EM}}{\partial C}, H = \frac{\partial W_{EM}}{\partial B}$ FSN $dA = \sigma_{EM}^{(out)} n da$ \checkmark Coupled Interfaces Solid Mechanics: Solid Mechanics (solid) Magnetic fields: \bullet	•	

EXAMPLES Full Transient, Nonlinear Analysis

A full transient analysis allows for the modeling of the total harmonic distortion, the intermodulation distortion, and the dynamic BL curve. A moving mesh is used to capture the geometry changes with time.

ID M Q M かけ自命 (R) (R) (R) (R)		loudspeaker_driver_transient.mph - COMSOL Multi
File Home Definitions Geometry Sketch Materials	Physics Mesh Study Results Developer	
Application Model Component Add Parameters	A= Variables • A variable Utilities • (*) Functions • P Parameter Case Definitions • Definitions • D	
Builder Manager 1 • Component • •	Pi Parameter Case All Materia	
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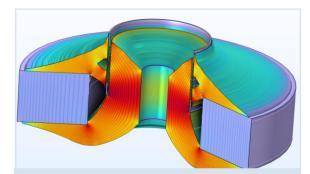
EXAMPLES Lumped Parameter Modeling

The speaker driver in the headphone is modeled through a lumped circuit and is coupled to a 3D pressure acoustics model using the *Interior Lumped Speaker Boundary* condition.

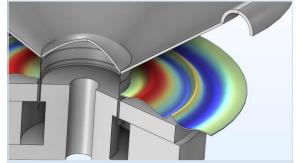
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File Home Definitions Geometry Materials Physics	Mesh Study Results Developer					
A E Component Add Parameters	a= Variables • a₀ Variable Utilities • ⊗ Functions • •₁ Parameter Case Definitions	Build All Geometry	Add Material Materials	Pressure Acoustics, Frequency Domain + Physics Physics	Build Mesh Mesh 1 • Mesh	Compute Study Frequency d Study
Model Builder	Settings		* #	Graphics Sound Pressure L		
	Interior Lumped Speaker Boundary	(···		@ Q @ ▼ 🕀 🔸 🗵	y lyz 🔯 🔿 🗸	
 Seadphone_artificial_ear.mph (root) Image: Contemporarily and Image and Image	Label: Interior Lumped Speaker Bounda	iry 1	E	freq=12500 Hz	7	
P1 Model parameters P1 Perforated plates parameters	 Boundary Selection 					
Pi Thiele-Small Parameters	Selection: Moving membrane		•			
	150 151 152 153 156 157	یں ہے۔ ج				
 Voltage Source 1 (V1) 	Override and Contribution				W }	
Resistor 1 (R1)					N I Ê	
Resistor 2 (<i>R2</i>)	▼ Equation					
 Inductor 1 (L 1) Resistor 3 (R3) 	Show equation assuming:					
2022 Inductor 2 (<i>L2</i>)	Study 1 - Frequency domain, Frequence	y Domain	•			
 	$\begin{split} F_{ax} &= \int (p_{t,down} - p_{t,up}) \mathbf{e}_{ax} \cdot \mathbf{n} dA \\ v_{ax} &= I_{cir} [m/s/A] \\ v_{cir} &= -F_{ax} [V/N] \end{split}$					
 Operation of the second second	 Speaker Geometry 					
Pressure Acoustics 1 Pressure Hard Boundary (Wall) 1	Speaker area:					
Initial Values 1	Selected boundaries		•			
🥃 Eardrum Impedance	Speaker axis direction:					
Skin impedance	eax User defined		•			1
Interior Sound Hard Boundary (Wall) 1 Interior Perforated Plate 1	1		x			
🧧 Interior Perforated Plate 2	0		y			
🔚 Interior Perforated Plate 3	0		z			
🕞 Interior Lumped Speaker Boundary 1						
 Poroelastic Waves (pelw) Multiphysics 	▼ Circuit				() S ()	C.S.S.
Manaphysics	I _{cir} Current (cir/lvsU1)		1			
🔺 \infty Study 1 - Frequency domain				z		
Xistep 1: Frequency Domain Mrs. Solver Configurations Job Configurations Mexatly Abb Configurations Mexatly				y x		

EXAMPLES Optimization Analysis

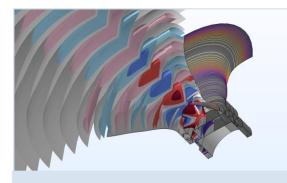
These tutorial models demonstrate how optimization methods can be used to design loudspeaker drivers and waveguides for the desired performance.



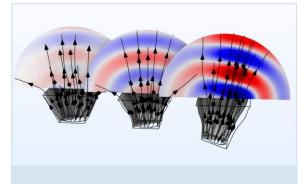
Optimization of a magnetic circuit.



Loudspeaker spider optimization.



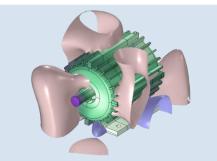
Tweeter dome and waveguide shape optimization.



Shape optimization of a rectangular loudspeaker horn in 3D.

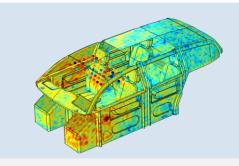
Automotive Acoustics & NVH

Automotive Acoustics Applications



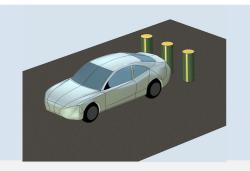
Noise and Vibrations

- Squeak and rattle noise
- Aeroacoustic noise
- Electric engine noise
- Tire noise



Car Cabin Acoustics

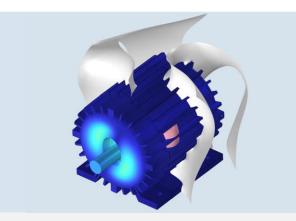
- Car cabin stereo
- Acoustic environment and personal sound zones



Sensors

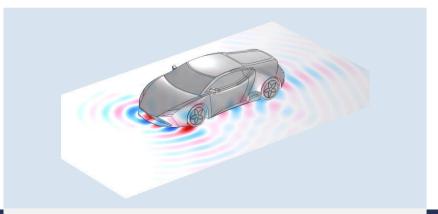
- Ultrasonic parking sensors
- Surface acoustic wave (SAW) tire pressure sensors

Solutions for Automotive Acoustics



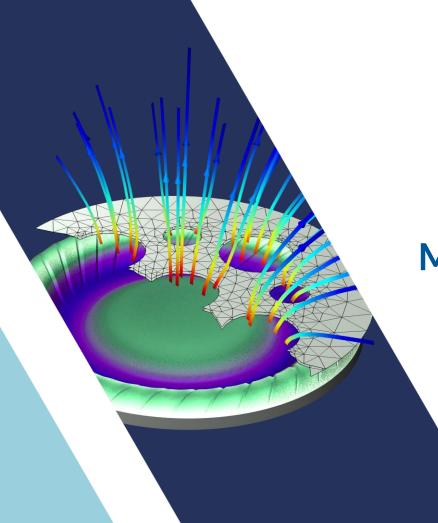
Multiphysics

- Acoustic–structure interaction
- Porous materials
- Electroacoustics
- Piezoelectricity



Multimethod

- Finite element method (FEM)
- Boundary element method (BEM)
- Ray tracing
- Time-explicit discontinuous Galerkin method (dG-FEM)



Microacoustics

INTRODUCTION What Is Microacoustics?

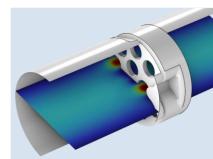
Acoustics where the characteristic geometric length scales are comparable to or smaller than the thermal and viscous acoustic boundary layers

Thermoviscous Acoustic Features

$$\begin{split} &i\omega\rho_{t} + \nabla \cdot (\rho_{0}\mathbf{u}t) = 0\\ &i\omega\rho_{0}\mathbf{u}t = \nabla \cdot \boldsymbol{\sigma}\\ &\rho_{0}C_{p}(i\omega\tau_{t} + \mathbf{u}t \cdot \nabla\tau_{0}) \cdot \alpha_{p}\tau_{0}(i\omega\rho_{t} + \mathbf{u}t \cdot \nabla\rho_{0})\\ &\boldsymbol{\sigma} = -\rho_{t}\mathbf{I} + \mu \Big(\nabla\mathbf{u}t + (\nabla\mathbf{u}t)^{\mathsf{T}}\Big) \cdot \Big(\frac{2}{3}\mu \cdot \mu_{\mathsf{B}}\Big) (\nabla \cdot \mathbf{u})\\ &\rho_{t} = \rho_{0}(\beta_{\mathsf{T}}\rho_{t} - \alpha_{p}\tau_{t}) \end{split}$$

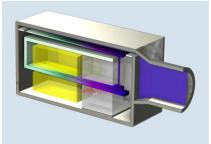
Thermoviscous Effects

Full linearized Navier– Stokes formulation, thermoviscous boundary layer impedance (BLI), and narrow region acoustics



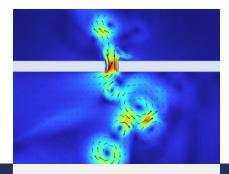
Ports

Port conditions to excite waveguides consistently and to analyze a subsystem in term of its transfer impedance



Multiphysics

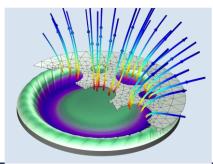
Coupling to structures and pressure acoustics for transducer modeling



Nonlinear

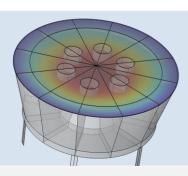
Nonlinear effects included in the time domain to model distortion and added resistive losses

Thermoviscous Acoustic Applications



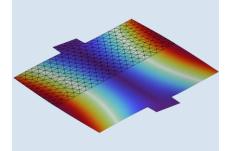
Microspeakers

Microspeakers and their operation, as well as integration into smart devices, hearing aids, and more



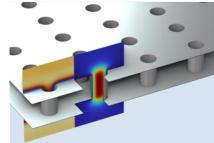
Microphones

Microphones and their operation, as well as integration into devices



MEMS

Operation of MEMS systems such as microphones and resonators

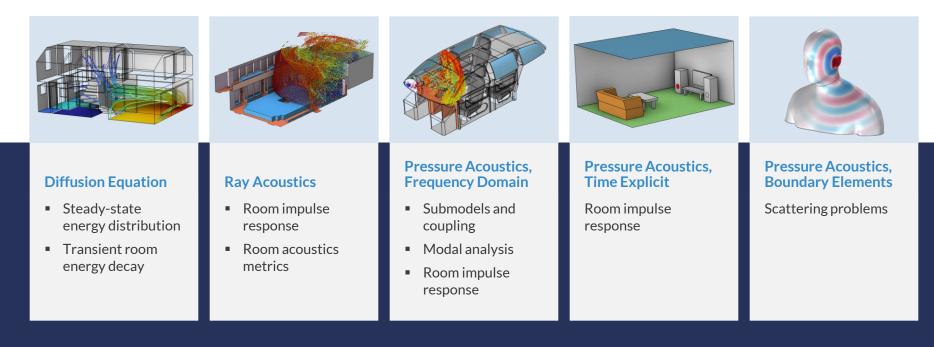


Perforates

Acoustic properties of perforates and microperforated plates (MPP); transfer impedance, impedance, and absorption

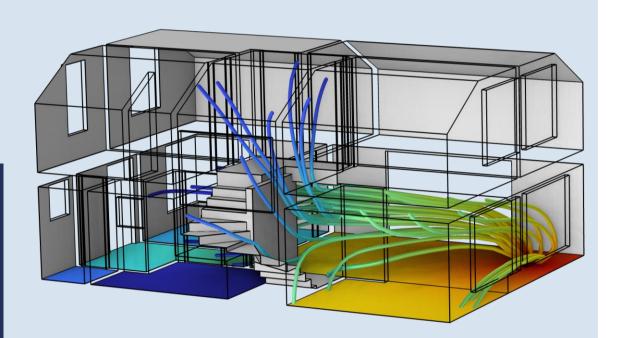
Room Acoustics for Large & Small Volumes

Acoustics Module Functionality



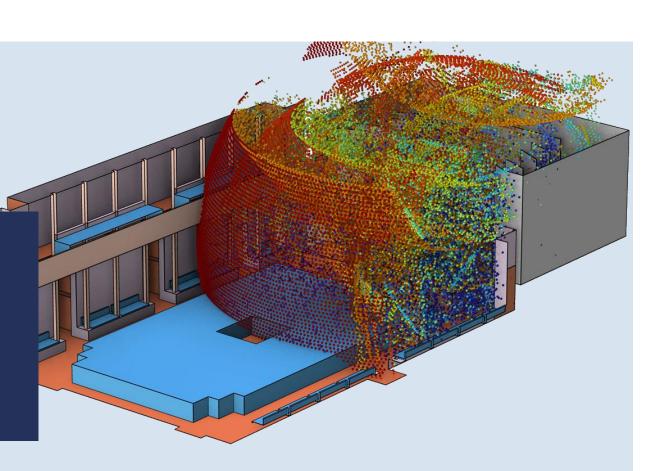
ACOUSTIC ENERGY Diffusion Equation

For broadband or octave band



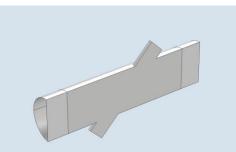
HIGH FREQUENCY Ray Acoustics

Intensity and power



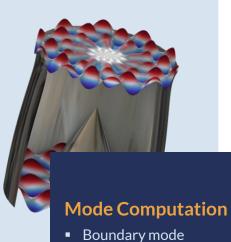
Aeroacoustics & Flow-Induced Noise

Aeroacoustic Capabilities

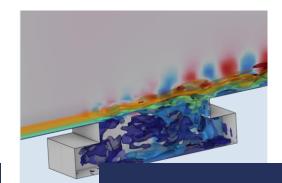


Convected Acoustics

- Acoustic propagation in the presence of a stationary background flow
- Convection, diffraction, and refraction by the flow



- Boundary mode interface to identify propagating and nonpropagating modes in ducts
- Essential for source characterization



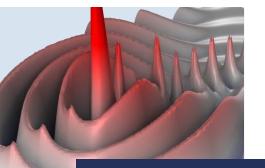
Flow-Induced Noise

- Lighthill's acoustic analogy
- Acoustic wave equation (AWE)

Convected Acoustics

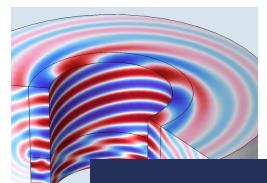
Linearized Navier-Stokes

- Detailed resolution of boundary layer effects and energy transport
- Propagation in all compressible fluids



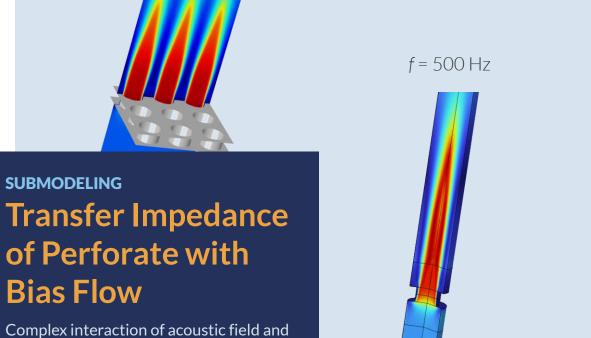
Linearized Euler

 Convected acoustic propagation in ideal gases with the linearized Euler equations



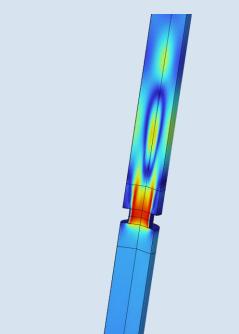
Linearized Potential Flow

- Convected acoustic propagation in ideal irrotational potential flows
- Ideal for fast analysis



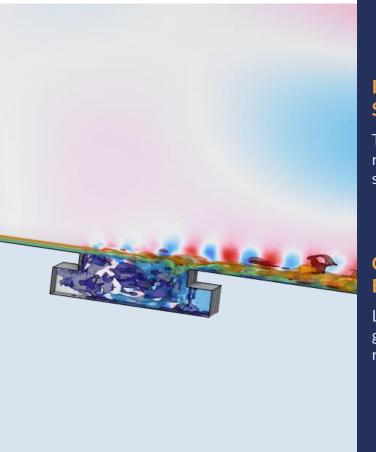
flow gradients through reactive terms in the linearized Navier–Stokes equations

$f = 5000 \, \text{Hz}$



Flow-Induced Noise

- Lighthill's acoustic analogy
- Acoustic wave equation (AWE)
- Acoustic sources extracted from large eddy simulation (LES): CFD Module
- Dedicated transient mapping study



Resolve Time and Space

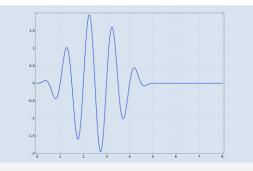
The LES model needs to resolve the flow in both space and time.

Computational Effort

LES simulations require good computational resources.

Ultrasound & Nondestructive Testing

Modeling Ultrasonic Wave Propagation in the Time Domain



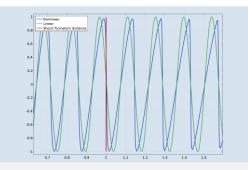
Signal Type

- Pulses
- Modulated sinusoidal signals



Operating Principle

- Sonic reflection (pulse-echo) measurement
- Time of flight computation



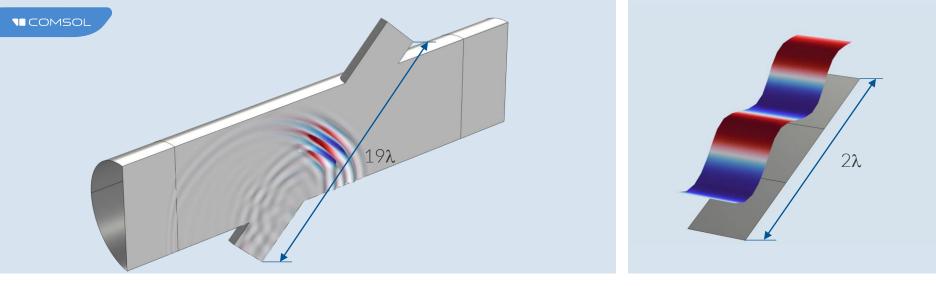
Nonlinear Effects

- High harmonic generation
- Shock waves

Physics Interfaces for Modeling Ultrasound



 Convected Wave Equation, Time Explicit



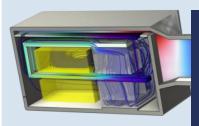
Time-Explicit Discontinuous Galerkin FEM (dG-FEM)

- Suited to acoustically large problems ($L \gg \lambda$)
- Uses higher-order discretization (4th order by default)
- Memory lean and high-performance computing (HPC) enabled

The COMSOL[®] Software Is the Right Tool for the Job



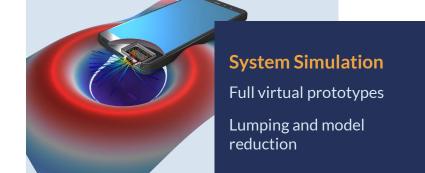
Combine and use the strength of different numerical methods

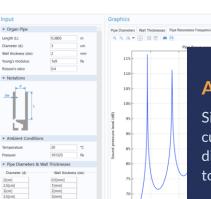


Multiphysics

Make sure that most physics can be easily and flexibly coupled

▼ Info





Apps

Simulation applications with custom user interfaces help distribute development tasks to nonexperts